



Printed Circuit Boards  
Interconnection Carriers

**PRINTED CIRCUIT BOARDS**

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**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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08 184 FR4 35 L20.35 L36.35 P10

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

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Layers	in $\mu$	Material	Build-Up	Assembly
Layer-1	35 $\mu$	Copper	<p>(100 <math>\mu</math> PrePreg-Type: 2125)</p>	A1
	100 $\mu$	Prepreg		
	100 $\mu$	Prepreg		
Layer-2	35 $\mu$	Copper		A2
	200 $\mu$	L-FR4		
Layer-3	35 $\mu$	Copper		
	100 $\mu$	Prepreg		A3
	100 $\mu$	Prepreg		
Layer-4	35 $\mu$	Copper		
	360 $\mu$	L-FR4		B
Layer-5	35 $\mu$	Copper		
	100 $\mu$	Prepreg		
	100 $\mu$	Prepreg		A3
Layer-6	35 $\mu$	Copper		
	200 $\mu$	L-FR4		
Layer-7	35 $\mu$	Copper		A3
	100 $\mu$	Prepreg		
	100 $\mu$	Prepreg		
Layer-99	35 $\mu$	Copper		

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